PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT7598730

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
ABHISHEK PRAMOD PATIL	07/29/2019
YONGCHUN XIAO	07/09/2019
RAVI GIDVANI	07/12/2019
SANDIP HOMCHAUDHURI	08/28/2019
PRADEEP KUMAR YENGANTI	08/19/2019
ARUL DAVIDSON EMMANUEL	07/11/2019
JAMES SIMON CHO	07/10/2019
PADMANABHAN VENKATARAMAN KARTHIC	07/11/2019
GEORGE CHERIAN	07/29/2019
ALFRED ASTERJADHI	07/23/2019
JOUNI KALEVI MALINEN	07/20/2019

RECEIVING PARTY DATA

Name:	QUALCOMM INCORPORATED
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121-1714

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17814470

CORRESPONDENCE DATA

Fax Number: (303)473-2720

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3034732700
Email: dlwilliams@hollandhart.com
Correspondent Name: HOLLAND & HART LLP/QUALCOMM
Address Line 1: P.O. BOX 11583
Address Line 4: SALT LAKE CITY, UTAH 84147

ATTORNEY DOCKET NUMBER:	PW467IN.US* (83043.2078)
NAME OF SUBMITTER:	J. SCOTT KARREN
SIGNATURE:	/J. Scott Karren/
DATE SIGNED:	10/19/2022

Total Attachments: 28
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ASSIGNMENT

WHEREAS, WE,

1. **Abhishek Pramod PATIL**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

2. **Yongchun XIAO**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

3. **Ravi GIDVANI**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

4. **Sandip HOMCHAUDHURI**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

5. **Pradeep Kumar YENGANTI**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

6. **Arul Davidson EMMANUEL**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

7. **James Simon CHO**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

8. **Padmanabhan Venkataraman KARTHIC**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

9. **George CHERIAN**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

10. **Alfred ASTERJADHI**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

11. **Jouni Kalevi MALINEN**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **RECEPTION OF MANAGEMENT FRAMES FOR MULTIPLE BASIC SERVICES SETS (BSSs)** (collectively the "**INVENTIONS**") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter "**ASSIGNEE**"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to

said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). **16/505,506** filed **July 8, 2019**, Qualcomm Reference No. **184094** and all provisional applications relating thereto, together with, Indian Provisional Application No(s). **201841025518** filed **July 9, 2018**, Qualcomm Reference No. **184094IN1** (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any

infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, on 7/29/19
City, State Date
Abhishek Pramod PATIL

Done at ____________, on ____________
City, State Date
Yongchun XIAO

Done at ____________, on ____________
City, State Date
Ravi GIDVANI

Done at ____________, on ____________
City, State Date
Sandip HOMCHAUDHURI

Done at ____________, on ____________
City, State Date
Pradeep Kumar YENGANTI

Done at ____________, on ____________
City, State Date
Arul Davidson EMMANUEL

Done at ____________, on ____________
City, State Date
James Simon CHO

Done at ____________, on ____________
City, State Date
Padmanabhan Venkataraman KARTHIC

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, on 7/29/19
City, State Date
George CHERIAN

Done at SAN DIEGO CA on 07/23/2019
City, State Date
Alfred ASTERJADHI

Done at ______________, on ______________
City, State Date
Jouni Kalevi MALINEN

ASSIGNMENT

WHEREAS, WE,

1. **Abhishek Pramod PATIL**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

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11. **Jouni Kalevi MALINEN**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **RECEPTION OF MANAGEMENT FRAMES FOR MULTIPLE BASIC SERVICES SETS (BSSs)** (collectively the "**INVENTIONS**") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter "**ASSIGNEE**"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to

said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). **16/505,506** filed **July 8, 2019**, Qualcomm Reference No. **184094** and all provisional applications relating thereto, together with, Indian Provisional Application No(s). **201841025518** filed **July 9, 2018**, Qualcomm Reference No. **184094IN1** (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any

infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at ____________, on ____________ ____________________
City, State Date **Abhishek Pramod PATIL**

Done at ____________, on ____________ ____________________
City, State Date **Yongchun XIAO**

Done at San Jose, CA, on 7/12/2019 ____________________
City, State Date **Ravi GIDVANI**

Done at ____________, on ____________ ____________________
City, State Date **Sandip HOMCHAUDHURI**

Done at ____________, on ____________ ____________________
City, State Date **Pradeep Kumar YENGANTI**

Done at ____________, on ____________ ____________________
City, State Date **Arul Davidson EMMANUEL**

Done at ____________, on ____________ ____________________
City, State Date **James Simon CHO**

Done at ____________, on ____________ ____________________
City, State Date **Padmanabhan Venkataraman KARTHIC**

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at ____________________, on ___________________ ____
City, State Date **George CHERIAN**

Done at ____________________, on ___________________ ____
City, State Date **Alfred ASTERJADHI**

Done at ____________________, on ___________________ ____
City, State Date **Jouni Kalevi MALINEN**

ASSIGNMENT

WHEREAS, WE,

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11. **Jouni Kalevi MALINEN**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **RECEPTION OF MANAGEMENT FRAMES FOR MULTIPLE BASIC SERVICES SETS (BSSs)** (collectively the "**INVENTIONS**") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter "**ASSIGNEE**"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to

said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). **16/505,506** filed **July 8, 2019**, Qualcomm Reference No. **184094** and all provisional applications relating thereto, together with, Indian Provisional Application No(s). **201841025518** filed **July 9, 2018**, Qualcomm Reference No. **184094IN1** (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any

infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at ____________________, on ________________ ______________________________
City, State Date **Abhishek Pramod PATIL**

Done at San Jose, CA, on 7/8/2019 ______________________________
City, State Date **Yongchun XIAO**

Done at ____________________, on ________________ ______________________________
City, State Date **Ravi GIDVANI**

Done at ____________________, on ________________ ______________________________
City, State Date **Sandip HOMCHAUDHURI**

Done at ____________________, on ________________ ______________________________
City, State Date **Pradeep Kumar YENGANTI**

Done at ____________________, on ________________ ______________________________
City, State Date **Arul Davidson EMMANUEL**

Done at ____________________, on ________________ ______________________________
City, State Date **James Simon CHO**

Done at ____________________, on ________________ ______________________________
City, State Date **Padmanabhan Venkataraman KARTHIC**

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Done at ____________________, on ____________________
City, State Date
____
George CHERIAN

Done at ____________________, on ____________________
City, State Date
____
Alfred ASTERJADHI

Done at TURKU, FINLAND, on 7/30/2019
City, State Date
____
Jouni Kalevi MALINEN

ASSIGNMENT

WHEREAS, WE,

1. **Abhishek Pramod PATIL**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

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11. **Jouni Kalevi MALINEN**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

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AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at ____________________, on ____________________ ______________________________
City, State Date **Abhishek Pramod PATIL**

Done at ____________________, on ____________________ ______________________________
City, State Date **Yongchun XIAO**

Done at ____________________, on ____________________ ______________________________
City, State Date **Ravi GIDVANI**

Done at SAN JOSE, CA, on 8/28/19 ______________________________
City, State Date **Sandip HOMCHAUDHURI**

Done at ____________________, on ____________________ ______________________________
City, State Date **Pradeep Kumar YENGANTI**

Done at ____________________, on ____________________ ______________________________
City, State Date **Arul Davidson EMMANUEL**

Done at ____________________, on ____________________ ______________________________
City, State Date **James Simon CHO**

Done at ____________________, on ____________________ ______________________________
City, State Date **Padmanabhan Venkataraman KARTHIC**

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at ____________________, on ____________________ ____
City, State Date **George CHERIAN**

Done at ____________________, on ____________________ ____
City, State Date **Alfred ASTERJADHI**

Done at ____________________, on ____________________ ____
City, State Date **Jouni Kalevi MALINEN**

ASSIGNMENT

WHEREAS, WE,

1. **Abhishek Pramod PATIL**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

2. **Yongchun XIAO**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

3. **Ravi GIDVANI**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

4. **Sandip HOMCHAUDHURI**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

5. **Pradeep Kumar YENGANTI**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

6. **Arul Davidson EMMANUEL**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

7. **James Simon CHO**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

8. **Padmanabhan Venkataraman KARTHIC**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

9. **George CHERIAN**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

10. **Alfred ASTERJADHI**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

11. **Jouni Kalevi MALINEN**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **RECEPTION OF MANAGEMENT FRAMES FOR MULTIPLE BASIC SERVICES SETS (BSSs)** (collectively the "**INVENTIONS**") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter "**ASSIGNEE**"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to

said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). **16/505,506** filed **July 8, 2019**, Qualcomm Reference No. **184094** and all provisional applications relating thereto, together with, Indian Provisional Application No(s). **201841025518** filed **July 9, 2018**, Qualcomm Reference No. **184094IN1** (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any

infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at ____________, on ____________
City, State Date
Abhishek Pramod PATIL

Done at ____________, on ____________
City, State Date
Yongchun XIAO

Done at ____________, on ____________
City, State Date
Ravi GIDVANI

Done at ____________, on ____________
City, State Date
Sandip HOMCHAUDHURI

Done at Fremont, CA, on 08/19/2019
City, State Date
Pradeep Kumar YENGANTI

Done at ____________, on ____________
City, State Date
Arul Davidson EMMANUEL

Done at ____________, on ____________
City, State Date
James Simon CHO

Done at ____________, on ____________
City, State Date
Padmanabhan Venkataraman KARTHIC

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at ____________________, on ____________________ ________________________________
City, State Date **George CHERIAN**

Done at ____________________, on ____________________ ________________________________
City, State Date **Alfred ASTERJADHI**

Done at ____________________, on ____________________ ________________________________
City, State Date **Jouni Kalevi MALINEN**

ASSIGNMENT

WHEREAS, WE,

1. **Abhishek Pramod PATIL**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

2. **Yongchun XIAO**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

3. **Ravi GIDVANI**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

4. **Sandip HOMCHAUDHURI**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

5. **Pradeep Kumar YENGANTI**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

6. **Arul Davidson EMMANUEL**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

7. **James Simon CHO**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

8. **Padmanabhan Venkataraman KARTHIC**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

9. **George CHERIAN**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

10. **Alfred ASTERJADHI**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

11. **Jouni Kalevi MALINEN**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **RECEPTION OF MANAGEMENT FRAMES FOR MULTIPLE BASIC SERVICES SETS (BSSs)** (collectively the "**INVENTIONS**") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter "**ASSIGNEE**"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to

said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). **16/505,506** filed **July 8, 2019**, Qualcomm Reference No. **184094** and all provisional applications relating thereto, together with, Indian Provisional Application No(s). **201841025518** filed **July 9, 2018**, Qualcomm Reference No. **184094IN1** (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any

infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at ____________, on ____________ ____________________
City, State Date **Abhishek Pramod PATIL**

Done at ____________, on ____________ ____________________
City, State Date **Yongchun XIAO**

Done at ____________, on ____________ ____________________
City, State Date **Ravi GIDVANI**

Done at ____________, on ____________ ____________________
City, State Date **Sandip HOMCHAUDHURI**

Done at ____________, on ____________ ____________________
City, State Date **Pradeep Kumar YENGANTI**

Done at ____________, on ____________ ____________________
City, State Date **Arul Davidson EMMANUEL**

Done at San Jose, CA, on July 10, 2019 ____________________
City, State Date **James Simon CHO**

Done at ____________, on ____________ ____________________
City, State Date **Padmanabhan Venkataraman KARTHIC**

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at ____________________, on ____________________ ____
City, State Date **George CHERIAN**

Done at ____________________, on ____________________ ____
City, State Date **Alfred ASTERJADHI**

Done at ____________________, on ____________________ ____
City, State Date **Jouni Kalevi MALINEN**

ASSIGNMENT

WHEREAS, WE,

1. **Abhishek Pramod PATIL**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

2. **Yongchun XIAO**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

3. **Ravi GIDVANI**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

4. **Sandip HOMCHAUDHURI**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

5. **Pradeep Kumar YENGANTI**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

6. **Arul Davidson EMMANUEL**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

7. **James Simon CHO**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

8. **Padmanabhan Venkataraman KARTHIC**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

9. **George CHERIAN**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

10. **Alfred ASTERJADHI**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

11. **Jouni Kalevi MALINEN**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **RECEPTION OF MANAGEMENT FRAMES FOR MULTIPLE BASIC SERVICES SETS (BSSs)** (collectively the "**INVENTIONS**") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter "**ASSIGNEE**"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to

said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). **16/505,506** filed **July 8, 2019**, Qualcomm Reference No. **184094** and all provisional applications relating thereto, together with, Indian Provisional Application No(s). **201841025518** filed **July 9, 2018**, Qualcomm Reference No. **184094IN1** (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any

infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at ________________, on ________________
City, State — Date
Abhishek Pramod PATIL

Done at ________________, on ________________
City, State — Date
Yongchun XIAO

Done at ________________, on ________________
City, State — Date
Ravi GIDVANI

Done at ________________, on ________________
City, State — Date
Sandip HOMCHAUDHURI

Done at ________________, on ________________
City, State — Date
Pradeep Kumar YENGANTI

Done at CHENNAI, TN, INDIA, on 11th JULY 2019
City, State — Date
Arul Davidson EMMANUEL

Done at ________________, on ________________
City, State — Date
James Simon CHO

Done at CHENNAI, TN, INDIA, on 11th JULY 2019
City, State — Date
Padmanabhan Venkataraman KARTHIC

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at ____________________, on ____________________ ____
City, State Date **George CHERIAN**

Done at ____________________, on ____________________ ____
City, State Date **Alfred ASTERJADHI**

Done at ____________________, on ____________________ ____
City, State Date **Jouni Kalevi MALINEN**